

COMPLETE LISTING OF THE CLAIMS

The following lists all of the claims that are or were in the above-identified patent application. The status identifiers respectively provided in parentheses following the claim numbers indicate the current statuses of the claims. In particular, claims having the status of "currently amended" are being amended in this reply.

Claims 1-8 (Canceled)

9. (Currently Amended) A method for fabricating an imaging device, comprising: fabricating electrical components of the imaging device on a substrate; forming an array of lenses on the substrate; forming a standoff on the substrate and surrounding the array of lenses; forming a barrier on the substrate between the standoff and the array of lenses; and attaching a cover to the standoff using an adhesive on a top surface of the standoff, wherein the barrier blocks the adhesive from extending onto the array of lenses.

10. (Original) The method of claim 9, wherein the substrate is a wafer, and fabricating the electrical components comprises processing the wafer to form a plurality of substantially identical integrated circuits, the imaging device being one of the integrated circuits.

11. (Original) The method of claim 10, further comprising: forming a plurality of arrays of lenses respectively on the plurality of the integrated circuits; forming a plurality of standoffs respectively surrounding the plurality of arrays of lenses; and attaching the cover to the plurality of standoffs.

12. (Currently Amended) The A method of claim 11, further for fabricating an imaging device, comprising:
fabricating electrical components of the imaging device on a substrate;
forming an array of lenses on the substrate;
forming a standoff on the substrate and surrounding the array of lenses;
attaching a cover to the standoff; and
cutting the cover while the cover is attached to the standoff, wherein cutting the

cover removes to remove a portion of the cover that overlies active circuitry in the substrate, wherein cutting the cover and leaves an underlying portion of the substrate intact.

13. (Currently Amended) The method of claim 12, further comprising cutting grooves in an underside of the cover before attaching the underside of the cover to the standoffs standoff, wherein cutting to remove the portion of the cover overlying active circuitry cuts from a topside of the cover down to the grooves.

14. (Original) The method of claim 10, further comprising sawing the wafer and the cover to form separated dies.

15. (Original) The method of claim 9, wherein forming the standoff comprises: depositing a layer of photoresist on the substrate; exposing the photoresist to define an area corresponding to the standoff; developing the photoresist to leave a portion of the photoresist from which the standoff is formed.

16. (Canceled)

17. (Amended) The A method of claim 16 for fabricating an imaging device, comprising:

fabricating electrical components of the imaging device on a substrate;
forming an array of lenses on the substrate;
forming a standoff on the substrate and surrounding the array of lenses; and
attaching a cover to the standoff, wherein attaching the cover comprises:
applying an adhesive to a top surface of the standoff; and
pressing the cover onto the standoff so that the adhesive binds the cover to the
standoff, wherein the adhesive contains filler particles having a size about equal to a
thickness of the adhesive between the cover and the standoff after the pressing step.

18. (Original) The method of claim 9, further comprising forming an optical coating on the cover before attaching the cover to the standoff.

19. (New) The method of claim 9, wherein the barrier is shorter than the standoff.

20. (New) The method of claim 9, wherein the standoff includes a vent, and attaching the cover to the standoff leaves the vent open to permit gas flow to a gap between the cover and the array of lenses, the gas flow preventing external pressure changes from distorting the cover.

21. (New) The method of claim 20, wherein the standoff and the barrier form a channel for the gas flow, and the channel includes one or more turns.

22. (New) The method of claim 12, further comprising:
fabricating the electrical components of a second imaging device on the substrate
forming a second array of lenses for the second imaging on the substrate; and
forming a second standoff on the substrate and surrounding the second array of lenses, wherein:
attaching the cover also attaches the cover to the second standoff; and
cutting the cover leaves separate portions of the cover over each of the imaging devices.

23. (New) The method of claim 17, further comprising forming a barrier on the substrate between the standoff and the array of lenses, wherein the barrier blocks the adhesive from extending onto the array of lenses during pressing of the cover onto the standoff.

24. (New) The method of claim 17, wherein the substrate is a wafer, and fabricating the electrical components comprises processing the wafer to form a plurality of substantially identical integrated circuits, the imaging device being one of the integrated circuits.

25. (New) The method of claim 24, further comprising:
forming a plurality of arrays of lenses respectively on the plurality of the integrated circuits;
forming a plurality of standoffs respectively surrounding the plurality of arrays of lenses; and
attaching the cover to the plurality of standoffs.

26. (New) The method of claim 25, further comprising cutting the cover while the cover is attached to the standoffs, wherein cutting the cover removes a portion of the cover that overlies active circuitry in the substrate and leaves separate portions of the cover respectively overlying the arrays of lenses.

27. (New) A method for fabricating an imaging device, comprising:
fabricating electrical components of the imaging device on a substrate;
forming an array of lenses on the substrate;
forming a standoff on the substrate and surrounding the array of lenses, the standoff including a vent and a channel for the gas flow, the channel including one or more turns; and

attaching a cover to the standoff, wherein attaching the cover leaves the vent and the channel open to permit gas flow to a gap between the cover and the array of lenses, the gas flow preventing external pressure changes from distorting the cover.

28. (New) The method of claim 27, wherein the substrate is a wafer, and fabricating the electrical components comprises processing the wafer to form a plurality of substantially identical integrated circuits, the imaging device being one of the integrated circuits.

29. (New) The method of claim 28, further comprising:
forming a plurality of arrays of lenses respectively on the plurality of the integrated circuits;
forming a plurality of standoffs respectively surrounding the plurality of arrays of lenses; and
attaching the cover to the plurality of standoffs.

30. (New) The method of claim 29, further comprising cutting the cover while the cover is attached to the standoffs, wherein cutting the cover removes a portion of the cover that overlies active circuitry in the substrate and leaves separate portions of the cover respectively overlying the arrays of lenses.